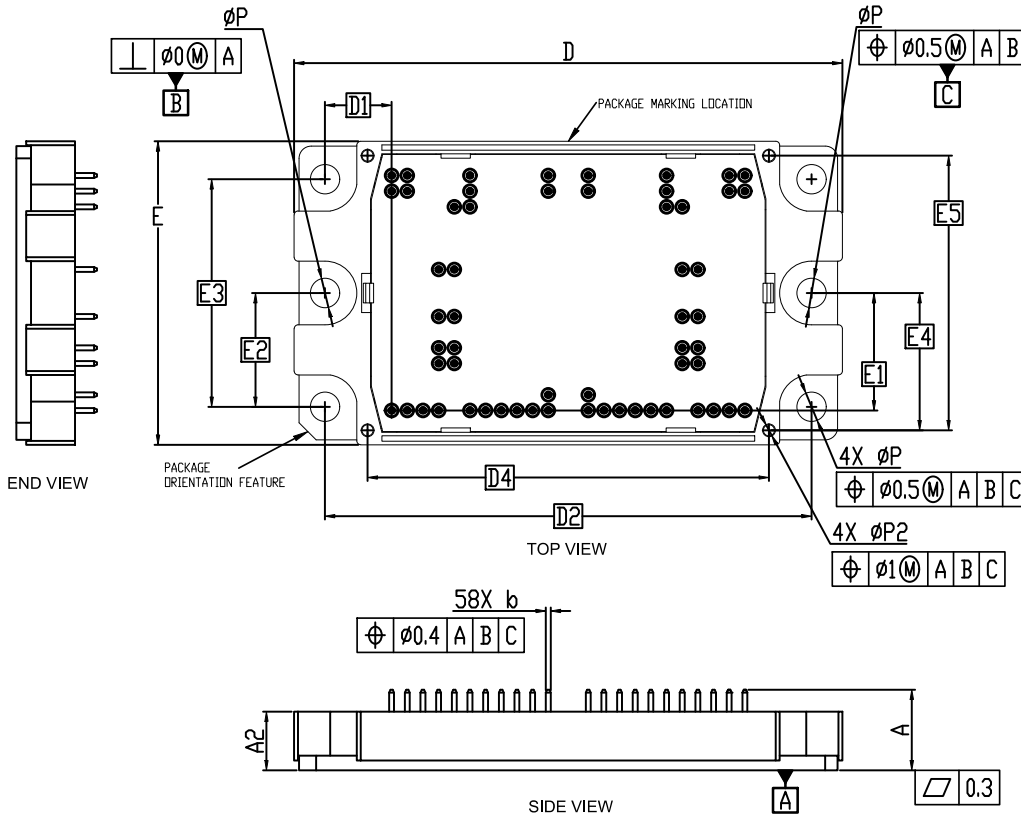


PIM58 112.00x62.00x12.00
CASE 180CZ
ISSUE O

DATE 30 JUL 2024

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5
2. All dimensions are in millimeters.
3. Pin-grid is 3.2mm.
4. Package marking is located on the side opposite the package orientation feature.
5. The pins are gold-plated solder pin.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	16.10	16.50	16.90
A2	11.70	12.00	12.30
b	0.95	1.00	1.05
D	111.60	112.00	112.40
D1	13.62 BSC		
D2	99.40 BSC		
D4	82.00 BSC		
E	61.60	62.00	62.40
E1	24.00 BSC		
E2	23.25 BSC		
E3	46.50 BSC		
E4	28.05 BSC		
E5	56.10 BSC		
P	5.90	6.00	6.10
P2	2.20	2.30	2.40

END VIEW

PACKAGE ORIENTATION FEATURE

TOP VIEW

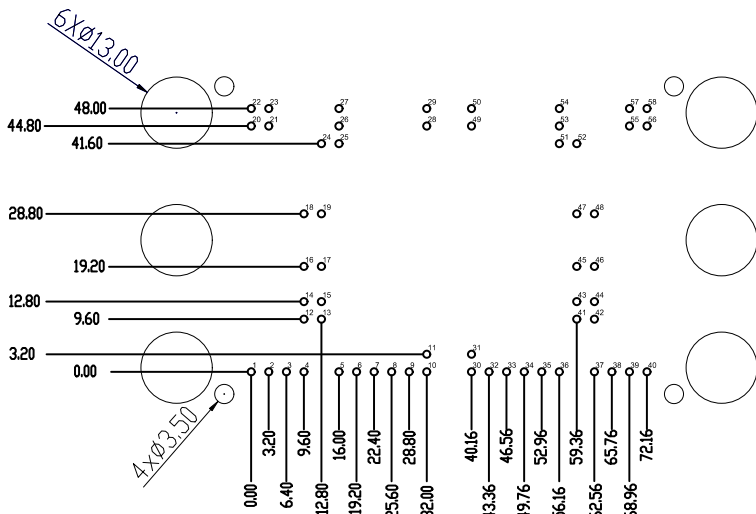
SIDE VIEW

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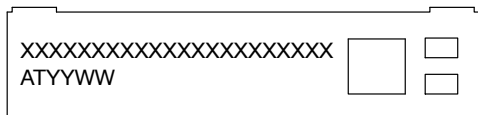
RECOMMENDED
MOUNTING PATTERN

* For additional information on our Pb-Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

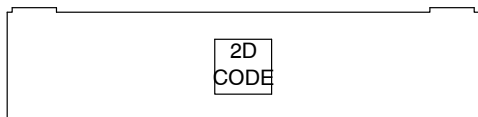
NOTE 2:

Pin table								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0	0	24	12.8	41.6	47	59.36	28.8
2	3.2	0	25	16	41.6	48	62.56	28.8
3	6.4	0	26	16	44.8	49	40.16	44.8
4	9.6	0	27	16	48	50	40.16	48
5	16	0	28	32	44.8	51	56.16	41.6
6	19.2	0	29	32	48	52	59.36	41.6
7	22.4	0	30	40.16	0	53	56.16	44.8
8	25.6	0	31	40.16	3.2	54	56.16	48
9	28.8	0	32	43.36	0	55	68.96	44.8
10	32	0	33	46.56	0	56	72.16	44.8
11	32	3.2	34	49.76	0	57	68.96	48
12	9.6	9.6	35	52.96	0	58	72.16	48
13	12.8	9.6	36	56.16	0			
14	9.6	12.8	37	62.56	0			
15	12.8	12.8	38	65.76	0			
16	9.6	19.2	39	68.96	0			
17	12.8	19.2	40	72.16	0			
18	9.6	28.8	41	59.36	9.6			
19	12.8	28.8	42	62.56	9.6			
20	0	44.8	43	59.36	12.8			
21	3.2	44.8	44	62.56	12.8			
22	0	48	45	59.36	19.2			
23	3.2	48	46	62.56	19.2			

GENERIC
MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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